PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Chien-An CHEN	03/07/2012
Wen-Jiun LIU	03/07/2012
Chun-Chieh LIN	03/07/2012
Hung-Wen SU	03/07/2012
Ming Hsing TSAI	03/07/2012
Syun-Ming JANG	03/07/2012

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	No. 8, Li-Hsin Rd. VI, Hsinchu Science Park
City:	Hsinchu
State/Country:	TAIWAN
Postal Code:	300

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13434691

OP $40.00 13434691

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	T5057-648U

NAME OF SUBMITTER:	Randy A. Noranbrock
Total Attachments: 2 source=efiledassgn#page1.tif source=efiledassgn#page2.tif	

Docket No. T5057-648U
TSMC2011-1267

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

1) **Chien-An CHEN**
2) **Wen-Jiun LIU**
3) **Chun-Chieh LIN**
4) **Hung-Wen SU**
5) **Ming Hsing TSAI**
6) **Syun-Ming JANG**

who has made a certain new and useful invention, hereby sells, assigns and transfers unto

TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD. having a place of business at **No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan (R.O.C.)**

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

MECHANISMS OF FORMING DAMASCENE INTERCONNECT STRUCTURES

(a) for which an application for United States Letters Patent was filed on 2012-03-29, and identified by United States Patent Application No. 13/434,691 ; or

(b) for which an application for United States Letters Patent was executed on ___________,

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) ______________ Name: Chien-An CHEN	3/7/2012 Date:
2) Wen Jiun Liu Name: Wen-Jiun LIU	2012.03.07 Date:
3) Chun-chieh Lin Name: Chun-Chieh LIN	2012-3-7 Date:

4) Hung-Wen Su
Name: Hung-Wen SU

3/7/12
Date:

5) Ming-Hsing Tsai
Name: Ming Hsing TSAI

3/7/12
Date:

6)
Name: Syun-Ming JANG

3/7/12
Date: